

TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π -MOSVI)

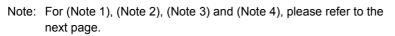
TPC8001

Lithium Ion Battery Applications Portable Equipment Applications Notebook PC Applications

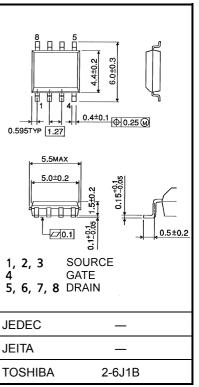
- Small footprint due to small and thin package
- Low drain-source ON resistance $: R_{DS} (ON) = 15 m\Omega (typ.)$
- High forward transfer admittance $|Y_{fs}| = 11 \text{ S (typ.)}$
- Low leakage current $: I_{DSS} = 10 \ \mu A \ (max) \ (V_{DS} = 30 \ V)$
- Enhancement-mode $: V_{th} = 0.8 \sim 2.0 \text{ V} (V_{DS} = 10 \text{ V}, \text{ ID} = 1 \text{ mA})$

Maximum Ratings (Ta = 25°C)

Character	ristics	Symbol	Rating	Unit	
Drain-source voltage		V _{DSS}	30	V	
Drain-gate voltage (R	t _{GS} = 20 kΩ)	V _{DGR}	30	V	
Gate-source voltage		V _{GSS}	±20	V	
Drain current	DC (Note 1)	۱ _D	7	А	
Diameditent	Pulse (Note 1)	I _{DP}	28	~	
Drain power dissipation	on (t = 10 s) (Note 2a)	PD	2.4	W	
Drain power dissipation	on (t = 10 s) (Note 2b)	PD	1.0	W	
Single pulse avalanch	ne energy (Note 3)	E _{AS}	64	mJ	
Avalanche current		I _{AR}	7	A	
Repetitive avalanche	energy Note 2a) (Note 4)	E _{AR}	0.24	mJ	
Channel temperature		T _{ch}	150	°C	
Storage temperature	range	T _{stg}	−55 to 150	°C	

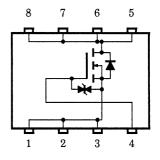


This transistor is an electrostatic sensitive device. Please handle with caution.



Weight: 0.080 g (typ.)

Circuit Configuration

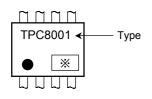


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Thermal Characteristics

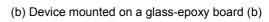
Characteristics	Symbol	Max	Unit
Thermal resistance, channel to ambient (t = 10 s) (Note 2a)	R _{th (ch-a)}	52.1	°C/W
Thermal resistance, channel to ambient (t = 10 s) (Note 2b)	R _{th (ch-a)}	125	°C/W

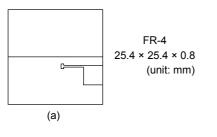
Marking (Note 5)

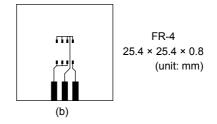


Note 1: Please use devices on condition that the channel temperature is below 150°C.

Note 2: (a) Device mounted on a glass-epoxy board (a)







Note 3: V_{DD} = 24 V, T_{ch} = 25°C (initial), L = 1.0 mH, R_G = 25 Ω , I_{AR} = 7 A

Note 4: Reptitve rating; pulse width limited by maximum channel temperature

Note 5: ● on lower left of the marking indicates Pin 1.

% shows lot number. (year of manufacture: last decimal digit of the year of manufacture, month of manufacture: January to December are denoted by letters A to L respectively.)

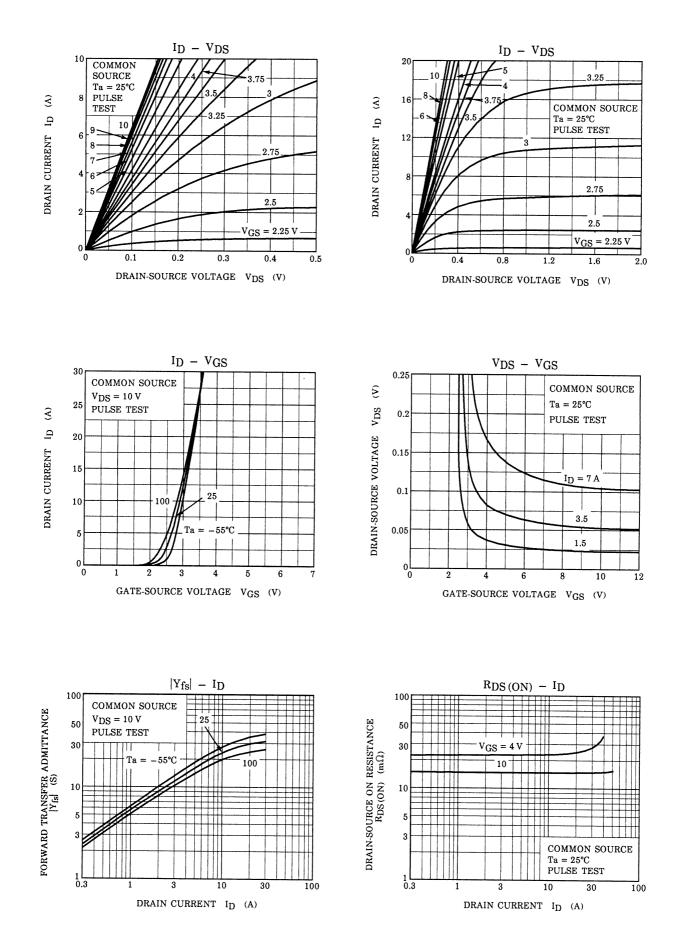
Electrical Characteristics (Ta = 25°C)

Charao	cteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	urrent	I _{GSS}	V _{GS} = ±16 V, V _{DS} = 0 V		—	±10	μA
Drain cut-off cu	rrent	I _{DSS}	V _{DS} = 30 V, V _{GS} = 0 V		_	10	μA
Drain-source br	reakdown voltage	V (BR) DSS	I _D = 10 mA, V _{GS} = 0 V	30	_	_	V
Gate threshold	voltage	V _{th}	V _{DS} = 10 V, I _D = 1 mA	0.8	_	2.0	V
		R _{DS (ON)}	V _{GS} = 4 V, I _D = 3.5 A		25	30	mΩ
Drain-source O	orain-source ON resistance		V _{GS} = 10 V, I _D = 3.5 A		16	20	mΩ
Forward transfe	r admittance	Y _{fs}	V _{DS} = 10 V, I _D = 3.5 A	5.5	11	_	S
Input capacitance Reverse transfer capacitance		C _{iss}			1250	_	pF
		C _{rss}	V _{DS} = 10 V, V _{GS} = 0 V, f = 1 MHz		190	_	
Output capacita	Output capacitance			_	760	_	
Switching time	Rise time	tr	$V_{GS} \stackrel{10 \text{ V}}{}_{0 \text{ V}} \stackrel{I_{D} = 3.5 \text{ A}}{}_{0 \text{ V}} \stackrel{V_{OUT}}{}_{RL} = 4.3 \Omega$	_	9	_	
	Turn-on time	t _{on}		_	17	_	- ns
	Fall time	t _f		_	24	_	
	Turn-off time	t _{off}	$V_{DD} = 15 V$ Duty $\leq 1\%$, t _w = 10 μ s	_	100	_	
Total gate charge (Gate-source plus gate-drain)		Qg		-	40	_	nC
Gate-source charge		Q _{gs}	$V_{DD} \approx 24 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 7 \text{ A}$	_	27	_	
Gate-drain ("miller") charge		Q _{gd}]		13	_	

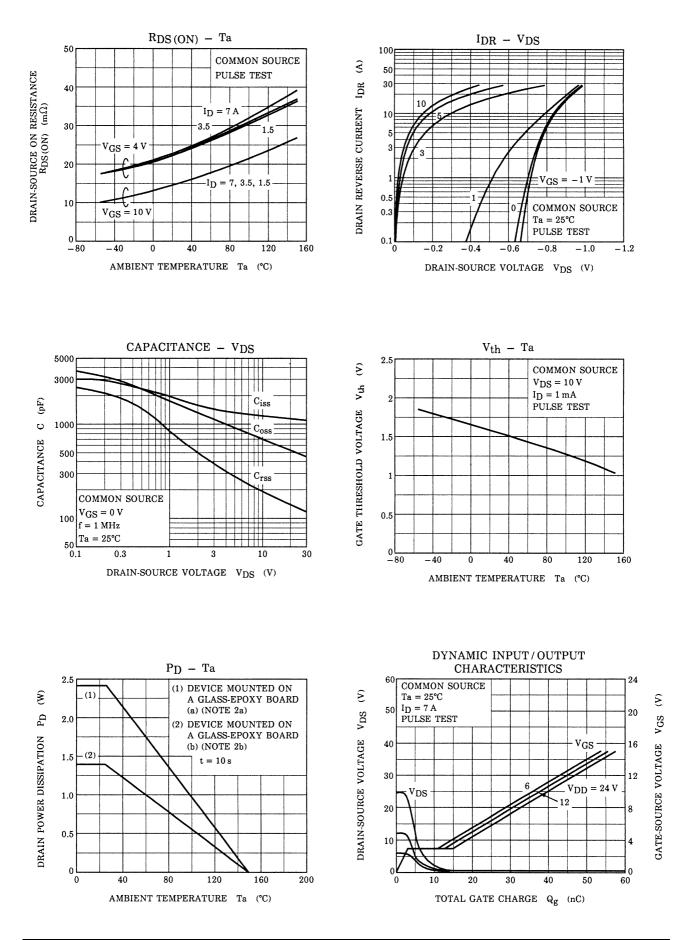
Source–Drain Ratings and Characteristics (Ta = 25°C)

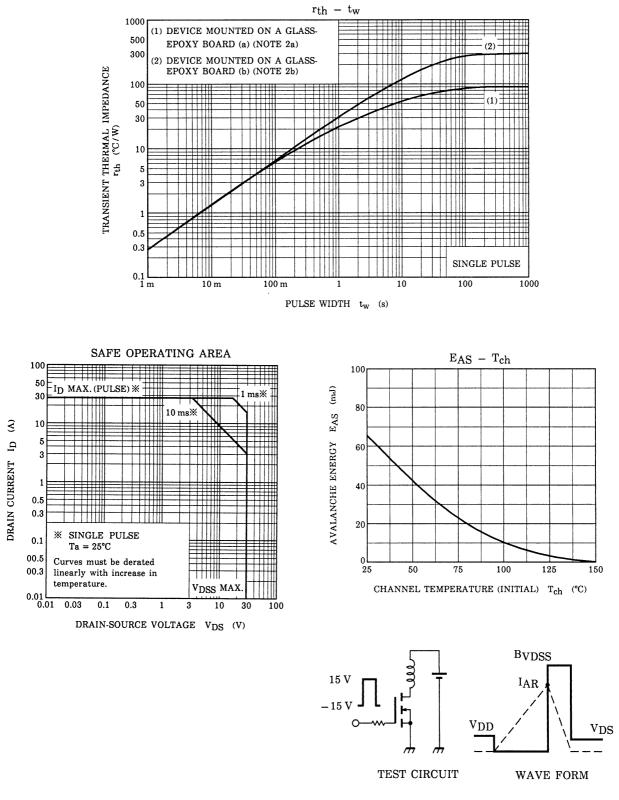
Charact	teristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Drain reverse current	Pulse (Note 1)	I _{DRP}	—	_	_	28	А
Forward voltage	(diode)	V _{DSF}	I _{DR} = 7 A, V _{GS} = 0 V			-1.2	V

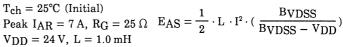
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